

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1-12 (Cancelled).

13. (Currently Amended) A plasma processing apparatus that performs plasma processing on a workpiece placed on an electrode provided inside a processing chamber, comprising:

an electrically conductive ring body encompassing the periphery of said workpiece placed on said electrode;

an electrically insulating ring body encompassing the periphery of said electrically conductive ring body;

a thermal conductivity adjusting member, for adjusting a thermal conductivity between the electrode and the electrically conductive ring body, provided between said electrode and said electrically conductive ring body; and

a means for pressure application that applies a pressure to said electrically conductive ring body toward said electrode and is capable of adjusting the level of pressure applied to said electrically conductive ring body,

wherein the means for pressure application is not exposed to the space of performing said plasma processing.

14. (Previously Presented) A plasma processing apparatus according to claim 13, further comprising a means for heat application provided at said electrically insulating ring body.

15. (Previously Presented) A plasma processing apparatus according to claim 13, wherein said thermal conductivity between said workpiece and said electrode is represented as Q,

wherein an area of a surface of said electrically conductive ring body contacting said plasma is represented as S1,

wherein an area of a surface of said electrically conductive ring body contacting said electrode is represented as S2, and

wherein said thermal conductivity adjusting member achieves a thermal conductivity R express as  $R = Q \times S1/S2$ .

16. (Cancelled).

17. (New) A plasma processing apparatus according to claim 13, further comprising a gas supply passage means through which a heat transfer gas is supplied to a space between said workpiece and said electrode.

18. (New) A plasma processing apparatus according to claim 13, wherein the means for pressure application sets the temperature at said electrically conductive ring body and the temperature at said workpiece roughly equal to each other.